



TECHNOLOGIES AND INDUSTRIAL MODELS TO RETAIN COMPETITIVENESS

ON THE OCCASION OF
smthybridpackaging



Industry 4.0 and emerging scenarios

10:00

- Opening - words of welcome
- Sophie B. de la Giroday, President, Wise Media
- Günther Trautzi, Key Account Manager, AIM Working Group System
*"Industry 4.0 – AutolD Systems will communicate with the real world (PC, IT, PLC):
AIM and OPC UA cooperation"*
- Andreas Binder, Head of Developing Department, Panmobil
"Werker 4.0 - an important connection for the 4.0 industry"
- Michael Ford, Senior Marketing Development Manager, Mentor Graphics
"Breaking the momentum of rigidity, waste and lost opportunities: A business case"

A closer look at materials

11:30

- Joseph Fjelstad, Founder, Verdant Electronics
"Aluminum - A Highly Attractive Substrate for Electronic Assemblies"
- Chris Palin, EMEA Manager, Humiseal
*"Improving Electronic Circuit Reliability in Harsh Environments and Creating your own
Test Specification"*
- Giuseppe Caramella, Technical Service Engineer Europe & IMEA, Henkel
"Technolmet Low Pressure Molding, a sustainable PCB protection solution"

Focus on Soldering

Phil Stoten, Publisher, EMSNow Media

14:00

- Gerjan Diepstraten, Advanced Technology Manager, Vitronics Soltec
"Establish a reliable soldering process for fine pitch through hole components"
- Cristian Tudor, Field Support Engineer, Central and Eastern Europe, Indium Corporation
"Void Reduction & Improved Heat Dissipation with Engineered Flux-Coated Solder Preforms"
- Speaker to be announced

SEM Working Group Round Table

A paradigm shift to sustain a legacy of environmental stewardship

SUSTAINABILITY SUMMIT

A ROADMAP TOWARDS OUR GLOBAL GOAL